

IN THE CLAIMS

Please amend the claims as follows:

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Claim 1 (Previously Presented): A wireless communication apparatus, comprising:

a mounting substrate including:

a duplexer connected to an antenna terminal;

a receiving amplifier and a transmitting amplifier individually connected to the duplexer;

a processor unit having a receiving processor and a transmitting processor respectively connected to the receiving and transmitting amplifiers in a region spaced from the receiving and transmitting amplifiers, wherein the processor unit monolithically integrates the receiving and transmitting processors and a ground region placed between the receiving and transmitting processors on a semiconductor chip; and

a baseband processor connected to the processor unit;

a shield case configured to cover the receiving amplifier, the transmitting amplifier, and the processor unit; and

a shield partition of a conductor provided in contact with the shield case, including,

a first partition provided from a top panel of the shield case to a surface of the mounting substrate so as to separate the receiving and transmitting amplifiers by extending from an end of the shield case, and

a second partition provided from the top panel to the surface of the mounting substrate by extending from another end of the shield case so as to face the first partition across the processing unit; and

a cut provided from the top panel in the shield case so as to overlay the processor unit between the first and second partitions,

wherein the ground region is electrically connected to the first and second partitions.

Claim 2 (Canceled).

Claim 3 (Previously Presented): The apparatus of claim 1, wherein the first partition is connected to a first ground terminal of the processor unit, the first ground terminal being connected to an end of the ground region and being provided in a vicinity of the first partition.

Claim 4 (Original): The apparatus of claim 3, wherein the second partition is connected to a second ground terminal of the processor unit, the second ground terminal being connected to other end of the ground region and being provided in a vicinity of the second partition.

Claim 5 (Original): The apparatus of claim 4, wherein at least a part of the respective first and second ground terminals are placed to face each other.

Claim 6 (Currently Amended): The apparatus of claim 1, wherein the shield case is connected to [[third]] ground terminals of the processor unit, the [[third]] ground terminals being connected to a receiving side ground region and a transmitting side ground region, respectively, of the receiving and transmitting processors provided on opposite ends of the semiconductor chip.

Claim 7 (Original): The apparatus of claim 4, wherein a conductive member is placed between the cut and a package of the processor unit in contact with the cut and the package.

Claim 8 (Original): The apparatus of claim 7, wherein an external ground electrode connected to at least one of the first and second ground terminals is provided on a surface of the package, the surface being in contact with the conductive member.

Claim 9-19 (Canceled).